

MANUFACTURING SPECIFICATIONS:

1. All materials must have a Tg of 180 degrees C or greater. PCB materials must be able to withstand lead-free soldering temperatures of up to 260 degrees C during the assembly operation.

Layer StackUp:

Layer 1 - Top Electrical Layer

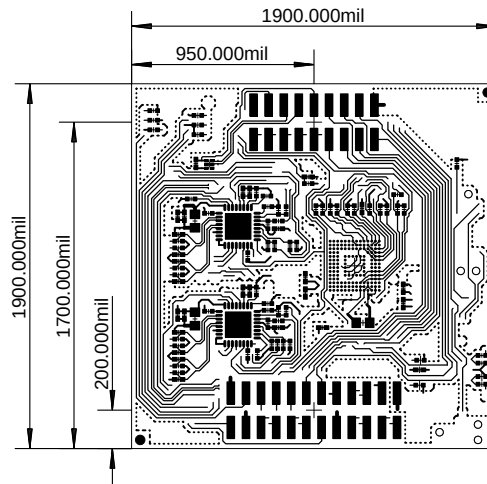
Layer 2 - GND Powerplane layer

Layer 3 - GND Powerplane layer

Layer 4 - Bottom Electrical Layer

4. Material thickness shall be 0.063 in. (1.60mm).

5. 2 oz. copper to be used on all layers.



BOARD LAYER 4 VIEWED FROM THE TOP SIDE